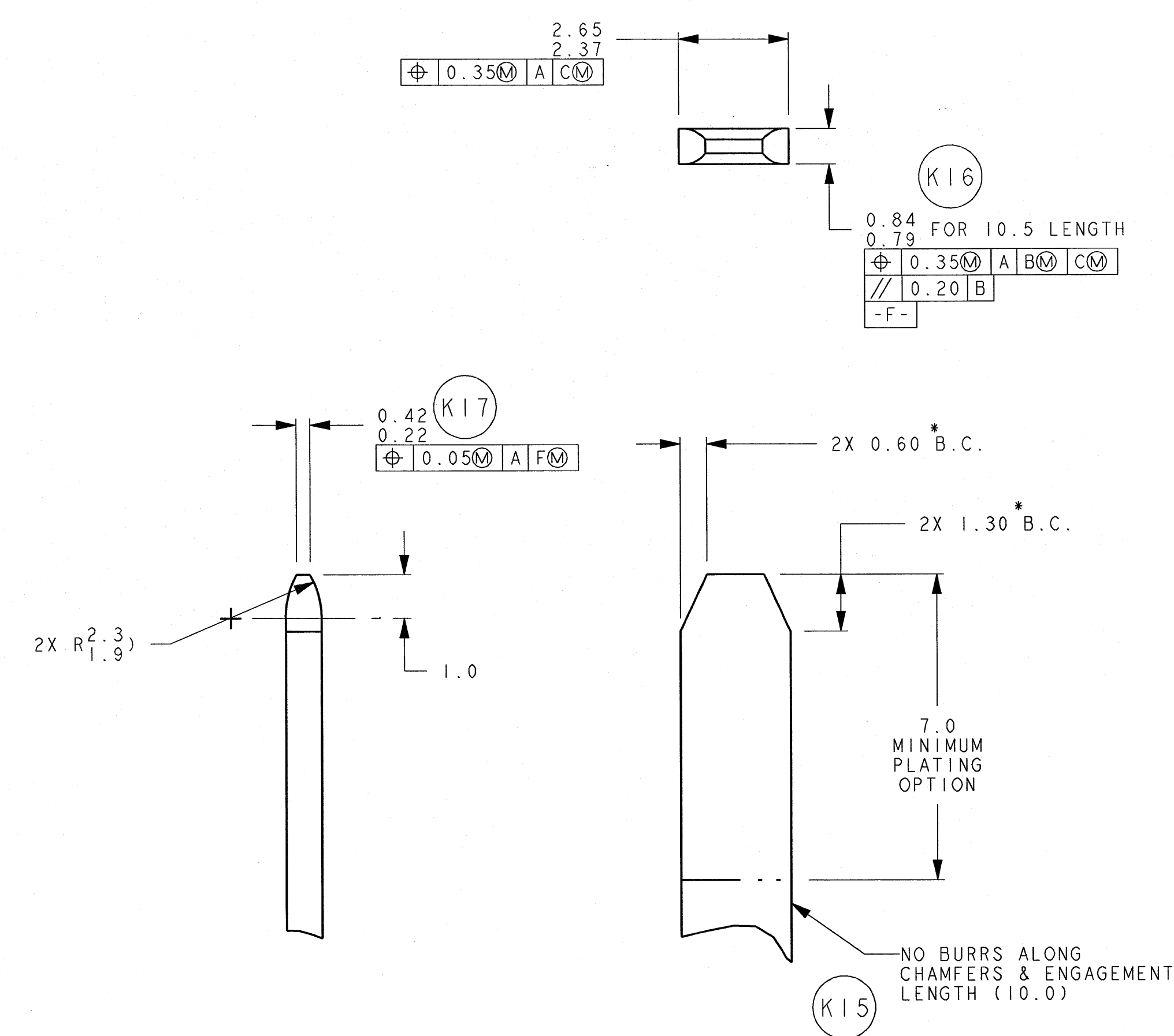




MALE TERMINAL (ENGAGEMENT AREA SCALE: 10X)

* B.C. INDICATES BEFORE COINING

BASE MATERIAL - HIGH CONDUCTIVITY COPPER ALLOY, MUST BE
APPROVED BY THE RESPONSIBLE ENGINEER

PLATING NOTES (CONTACT AREA)

TIN (125°C MAXIMUM CONTINUOUS TEMPERATURE)

A. HOT TIN DIP 0.5um To 2um (20uin To 80uin)
OR
B. POST ELECTRO MATE TIN
BARRIER PLATE (OPTIONAL FOR SOLDERABILITY) - UNDERPLATE
WITH COPPER 2.5um (100uin) MIN. THICKNESS
TOP LAYER 5.0um±.5um (200uin±100uin) TIN
PER ASTM B-545-83

PRECIOUS METAL: WHEN SPECIFIED (PER USCAR EWCAP PLATING REQUIREMENTS)

BARRIER PLATE - (OPTIONAL FOR SOLDERABILITY) UNDERPLATE
WITH COPPER 2.5um (100uin) MIN THICKNESS PER ATSM -- TBD

INTERMEDIATE LAYER #1 SULFAMATE DUCTILE NICKEL 1.27um ±.25um
(50uin - 100uin) THICK PER ASTM B699 TYPE 2

INTERMEDIATE LAYER #2 OPTIONAL 1.0um (40uin) MIN THICKNESS
PALLADIUM ELECTROPLATE PER ASTM B.TBD

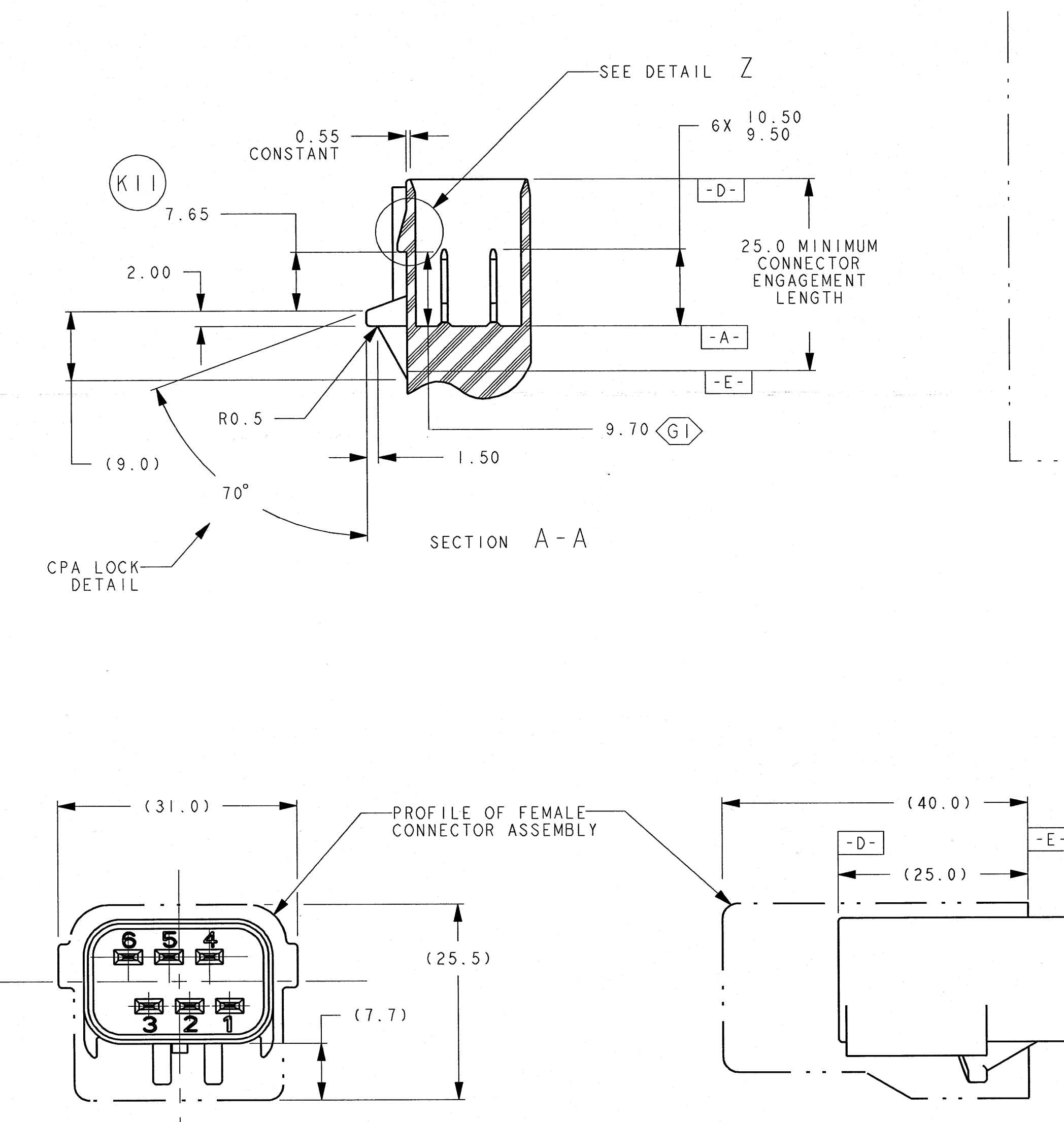
TOP LAYER 0.1um (40uin) MIN THICKNESS HARD GOLD OVER LAYER #2
0.75um (30uin) MIN THICKNESS HARD GOLD IF LAYER #2 IS NOT
APPLIED, PER ASTM B.TBD

FOR HEAVY DUTY DIESEL ENGINES: WHEN SPECIFIED

TOP LAYER 1.27um (50uin) MIN THICKNESS HARD GOLD ELECTROPLATE
PER ASTM B-488 TYPE 2 CODE "C" OVER INTERMEDIATE LAYER #1
OR
INTERMEDIATE LAYER #2 1.27um (50uin) MIN THICKNESS
PALLADIUM ELECTROPLATE

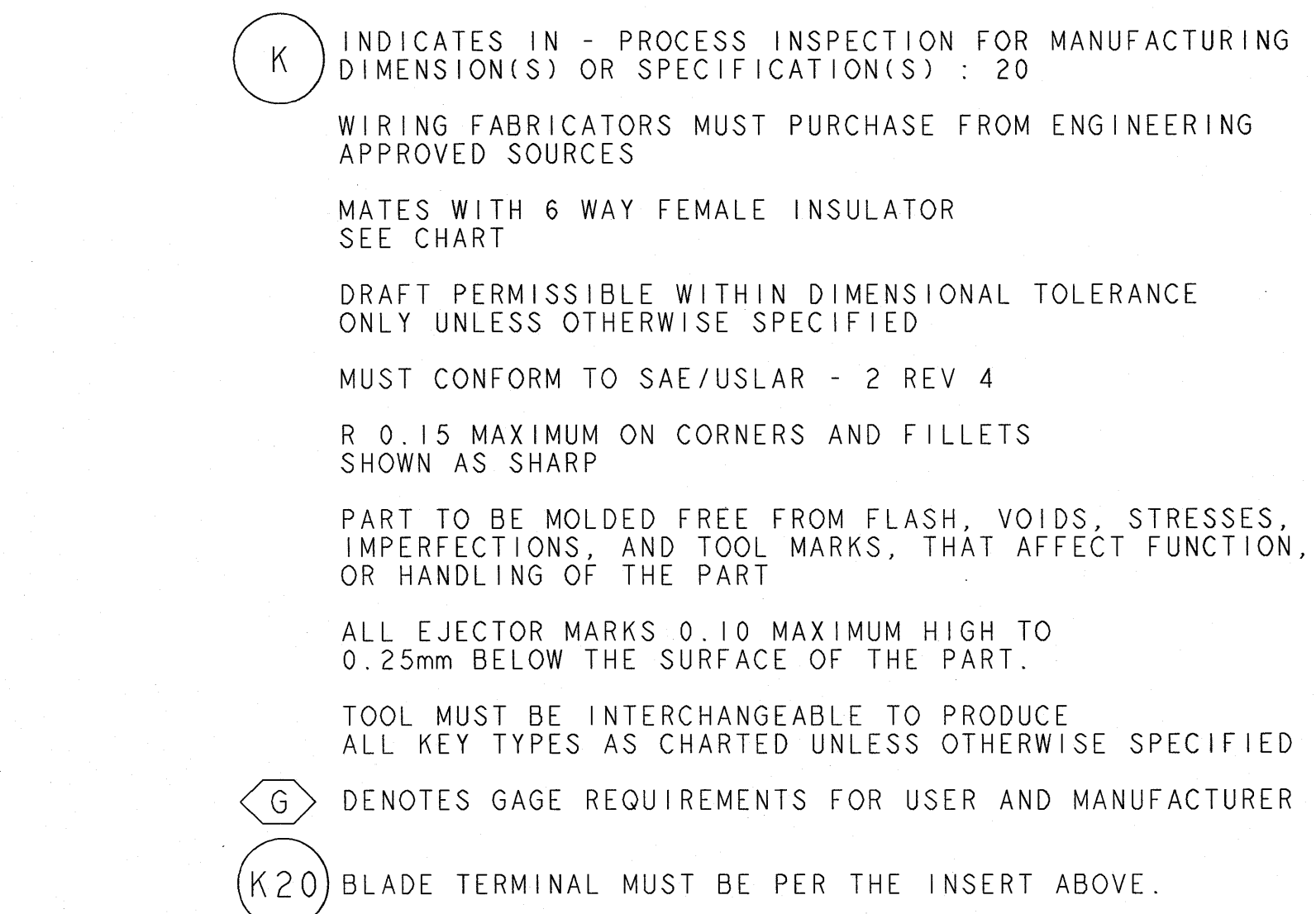
TOP LAYER 0.05um (2uin) MIN THICKNESS HARD GOLD ELECTROPLATE

NOTE: ABOVE NOTES RELATING TO MATERIAL AND
PLATING ARE FOR REFERENCE ONLY. PARTS
MUST BE VALIDATED TO CUSTOMER REQUIREMENTS.



(K18)

54200603	UN-SEALED	NATURAL	TYPE D
54200611	UN-SEALED		
54200602	UN-SEALED	DK. GRAY	TYPE C
54200610	UN-SEALED		
54200646	UN-SEALED	LT. GRAY	TYPE B
54200601	UN-SEALED		
54200609	SEALED	BLACK	TYPE A
54200600	SEALED		
54200626	SEALED		
54200600	UN-SEALED		
54200608	UN-SEALED	COLOR	POLARIZING OPTION
MATES WITH 6 WAY FEMALE	SEALED OR UN-SEALED		



UNCONTROLLED

_____	_____	_____	_____	_____
PART NUMBER F.C.I.	PART NUMBER	REV DATE	REV	DRAWING NUMBER
_____ CUSTOMER _____				

[illegible]